ESD5B5CL Low-Capacitance Bidirectional Micro Packaged TVS Diodes for ESD

DESCRIPTION

The ESD5B5CL is designed with Weipan Punch-Through process TVS technology to protect voltage sensitive compone -nts from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and m -any other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for us -e in high frequency designs such as USB 2.0 high speed, VGA, DVI, SDI and other high speed line applications.

This series has been specifically designed to protect sensit -ive components which are connected to data and transmission lines from overvoltage caused by ESD(electrostatic discharge), and EFT (electrical fast transients).

FEATURES

- ♦ Peak Power Dissipation 80 W (8 x 20 us Waveform).
- ♦ Stand-off Voltage: 5.0 V.
- \diamond Replacement for MLV (0603).
- ♦ Protects I/O Port.
- ♦ Low Clamping Voltage.
- ♦ Low Leakage.
- ♦ Low Capacitance.
- ♦ Low Body Height: 1.68mg.
- ♦ Low capacitance (<10pF) for high-speed interfaces.</p>
- \diamond No insertion loss to 1.0GHz.
- ♦ Response Time is < 1 ns.</p>
- ♦ Meets MSL 1 Requirements.
- ♦ ROHS compliant.
- Solid-state Punch-Through TVS Process technology.
- ♦ WeiPan technology.





APPLICATIONS

- ♦ High Speed Line :USB1.0/2.0, VGA, DVI, SDI.
- ♦ Serial and Parallel Ports.
- ♦ Notebooks, Desktops, Servers.
- ♦ Projection TV.
- ♦ Cellular handsets and accessories.
- ♦ Portable instrumentation.
- ♦ Peripherals.

MECHANICAL CHARACTERISTICS

- ♦ SOD-523 Package.
- ♦ Quantity Per Reel : 3,000pcs.
- ♦ Reel Size : 7 inch.
- ♦ Finish : Free.

DEVICE CHARACTERISTICS

Maximum ratings (Tamb=25 $^{\circ}$ CUnless Otherwise Specified)

| Parameter | Symbol | Value | Unit | | | |
|--|------------------|---------------|-------|--|--|--|
| Peak Pulse Power (tp=8/20µs waveform) | P _{PP} | 80 | Watts | | | |
| ESD Rating per IEC61000-4-2: Contact | | 8 | | | | |
| Air | | 15 | ΝV | | | |
| Lead Soldering Temperature | Τι | 260 (10 sec.) | °C | | | |
| Operating Temperature Range | Tj | -55 ~ 150 | °C | | | |
| Storage Temperature Range | T _{STG} | -55 ~ 150 | °C | | | |
| Lead Solder Temperature – Maximum (10 Second Duration) | Τι | 260 | °C | | | |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- *Other voltages may be available upon request.
- 1. Nonrepetitive current pulse, per Figure 1.

IEC COMPATIBILITY

 ♦ IEC61000-4-2 (ESD) ±15kV (air), ± 8kV (contact).

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♦ IEC61000-4-4 (EFT) 40A (5/50ns).

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| Electrical characteristics (Tamb=25°CUnless Otherwise Specified) | | | | | | | |
|--|------------------|------|------------------------|-------------------------|-----|------------------------------------|-----|
| Device (V) | | | V _{РТ} @ 1 mA | V _{sB} @ 50 mA | Vc | Capacitance | |
| | V _{RWM} | | (Volts) | (Volts) | @1A | @ V _R = 0 V, 1 MHz (pF) | |
| | (V) | (uA) | Min | Min | (V) | Тур | Max |
| JESD5B5CL | 5.0 | 2 | 6.0 | 5.3 | 9 | 3 | 6 |

Junction capacitance is measured in VR=0V,F=1MHz

| Symbol | Parameter |
|------------------|------------------------------------|
| V _{RWM} | Working Peak Reverse Voltage |
| V _{PT} | Punch-Through Voltage@ I_{PT} |
| V _{SB} | Snap-Back Voltage@ I _{SB} |
| Vc | Clamping Voltage @ IPP |
| IT | Test Current |
| Irm | Leakage current at VRWM |
| I _{PP} | Peak pulse current |
| Co | Off-state Capacitance |
| CJ | Junction Capacitance |



ELECTRICAL CHARACTERISTICS CURVE







Pulse Waveform



ESD5B5CL









TYPICAL APPLICATIONS



USB Protection For ESD

Junction Capacitance vs. Reverse Voltage





I/O Line Protection

SOD-523 PACKAGE OUTLINE & DIMENSIONS









| Dim | Millim | eters | Inches | | |
|-----|--------|-------|--------|--------|--|
| | Min | Max | Min | Max | |
| Α | 1.10 | 1.30 | 0.043 | 0.051 | |
| В | 0.70 | 0.90 | 0.045 | 0.053 | |
| C | 0.50 | 0.70 | 0.031 | 0.043 | |
| D | 0.25 | 0.35 | 0.004 | 0.012 | |
| J | 0.07 | 0.20 | 0.0028 | 0.0079 | |
| К | 0.15 | 0.25 | 0.006 | 0.010 | |
| S | 1.50 | 1.70 | 0.059 | 0.067 | |



Product Orientation (continued)



| Package | Chip Size | Pocket Size B0×A0×K0(mm) | Tape Width | Reel Diameter | Quantity Per Reel | PO | P1 |
|---------|--------------|-----------------------------|---------------|------------------|----------------------|-----|-----|
| SOD-523 | 1.60×0.8×0.6 | 1.75×0.95×0.75 | 8mm | 178mm(7") | 3000 | 4mm | 4mm |
| D0 | D1 | E | F | K | Т | W | |
| 1.5mm | 0.5mm | 1.75mm | 3.5mm | 0.70mm | 0.2mm | 8mm | |

The LEADER is a minimum of 100 components in length and it consists of empty cavities with sealed cover tape The TRAILER is a minimum of 100 components in length and it consists of empty cavities with sealed cover tape.

